Fraunhofer
ENAS

37th Chemnitz Seminar
»Electronic Packaging and Applications«

Program

Tuesday | June 13, 2023

12:30 – 12:40 pm	Welcome to 1st day | Dr. Maik Wiemer, Fraunhofer ENAS
12:40 – 1:05 pm	Die-to.wafer bonding | Tobias Wernicke, EV Group
1:05 – 1:30 pm	IR packaging based on anodic bonding with thin glass layers | Ulli Hansen, MSG Lithoglas GmbH
1:30 – 1:55 pm	State of the art and novel wafer level solder bumping techniques | Daniel Lieske, AEMtec GmbH
1:55 – 2:20 Uhr	Reliability of lead-free solders for die attach in automotive power modules | Sebastian König, Vitesco
2:20 – 3:00 pm	Coffee break
3:00 – 3:25 pm	Copper sinter pastes – Challenges and opportunities for power electronic assemblies | Sebastian Fritzsche, Heraeus Electronics
3:25 – 3:50 pm	Thin-film encapsulated IR emitter based on SON technology | Stefan Hampl, Infineon Technologies AG
3:50 – 4:15 pm	Embedded functional ceramics in LTCC, opportunities and challenges in packaging | Dr. Qaisar Khushi Muhammad, VIA Electronic GmbH
4:15 – 4:40 pm	Additive manufacturing and packaging technologies for flexible substrates towards wound treatment and diagnostics | Valeri Fitz, Fraunhofer ENAS

Wednesday | June 14, 2023

8:30 – 8:40 am	Welcome to 2nd day | Dr. Maik Wiemer, Fraunhofer ENAS
8:40 – 9:05 am	X-FAB approaches advanced packaging | Tino Jäger, X-FAB
9:05 – 9:30 am	Layer-by-layer self-assembly – A powerful tool for materials integration | Prof. Dr. Yvonne Joseph, TU Bergakademie Freiberg
9:30 – 9:55 am	Metrology for hybrid bonding | Thomas Schmidt, SÜSS MicroTec Solutions GmbH
9:55 – 10:45 am	Coffee break
10:45 – 11:10 am	Latest Progress of Plating Equipment for Al plating from ionic liquids | Mike Becker, NB Technologies GmbH
11:10 – 11:35 am	Tailor-made synthesis of organic mixed ionic-electronic conductors as active material in organic electrochemical transistors | Julian Hungenberg, Universität Bayreuth
11:35 – 12:00 pm	Biocompatible humidity sensor for smart farming | Moritz Schlagmann, Infineon Technologies AG
12:00 – 1:00 pm	Lunch break
1:00 – 1:25 pm	Heterogeneous integration & 3D packaging technology – by Nano Dimension | Mirko Sidoti, Nano Dimension
1:25 – 1:50 pm	Wafer level packaging based on wafer bonding and TSVs for advanced MEMS integration | Prof. Dr. Roy Knechtel, TU Schmalkalden
1:50 – 2:20 pm	Discussion
2:20 pm	Individual lab and window tours

Contact

Dr. Maik Wiemer
Phone +49 371 45001-233
maik.wiemer@enas.fraunhofer.de

Fraunhofer ENAS
Technologie-Campus 3
09126 Chemnitz | Germany

www.enas.fraunhofer.de